



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Toshifumi KIMBA et al.

Serial No. 09/734,737

Filed December 13, 2000

**Confirmation No. 4508**

Docket No. 2000-1706A

Group Art Unit 2877

Examiner Hoa Q. Pham

SUBSTRATE FILM THICKNESS  
MEASUREMENT METHOD, SUBSTRATE  
FILM THICKNESS MEASUREMENT  
APPARATUS AND SUBSTRATE  
PROCESSING APPARATUS

TECHNICAL DRAWINGS  
12/15/2003

**ELECTION OF INVENTION**

Assistant Commissioner for Patents,  
Washington, D.C.

Sir:

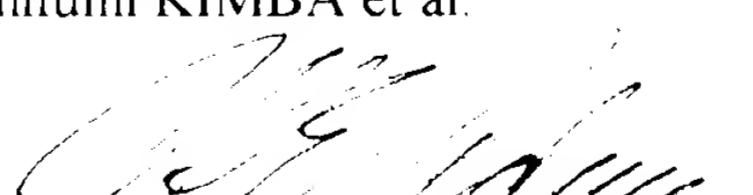
In response to the restriction requirement of January 15, 2003, Applicants in the above-referenced U.S. patent application hereby elect the invention of group I, corresponding to claims 1-18.

An early and favorable action on the merits is earnestly solicited.

Respectfully submitted,

Toshifumi KIMBA et al.

By:

  
Nils E. Pedersen  
Registration No. 33,145  
Attorney for Applicants

NEP/krl  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
February 11, 2003